

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			NEW RELEASE	02/28'12	Orlando

**CUSTOMER DRAWING**

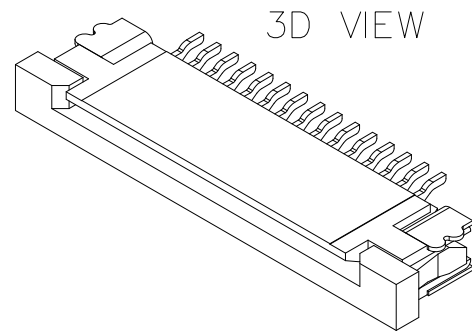
**RoHS Compliant**

ORDERING INFORMATION  
**FDS1025 - XX (11 R)**  
 ① ② ③

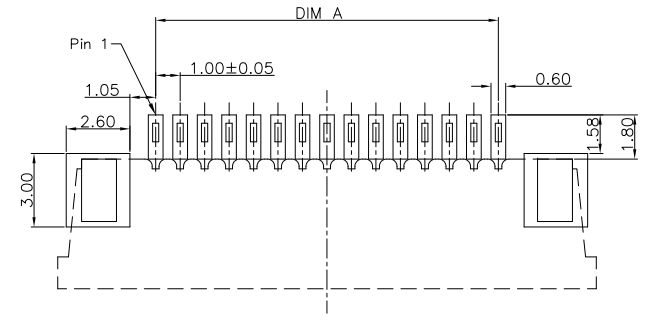
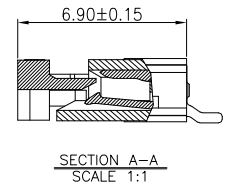
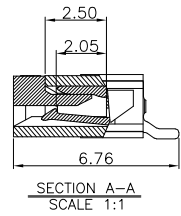
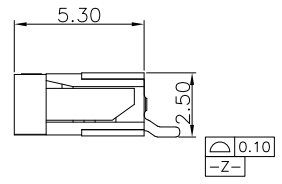
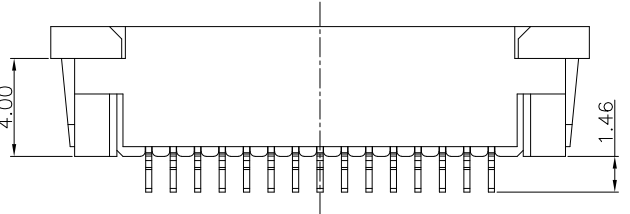
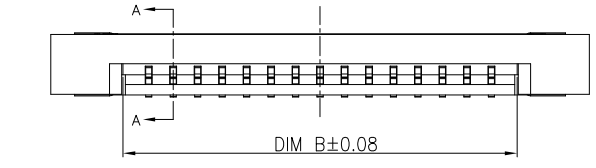
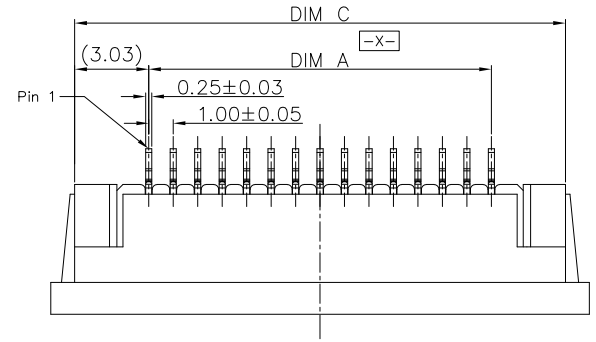
① **PRODUCT SERIES**  
 FPC/FFC CONN- Drawer type  
 Pitch 1.0mm / Height 2.5mm  
 Sub contact / SMT Type.

② **NUMBER OF CONTACTS**  
 04 TO 30

③ **PLATING & PACKING**  
 11 : Tin plated



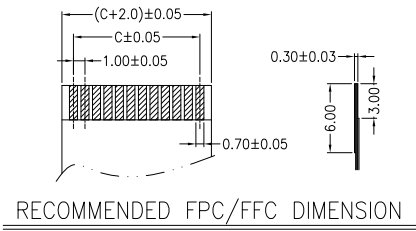
3D VIEW



RECOMMENDED P.C.B LAYOUT

Note:

1. Material
  - 1.1: Housing: High Temperature, LCP, UL94V-0.
  - 1.2: Actuator: High Temperature, LCP, UL94V-0.
  - 1.3: Contact: Copper Alloy.
  - 1.4: Fit: Copper Alloy.
2. Plating
  - 2.1: Contact: Tin plated over Nickel on contact area.  
Tin plated over Nickel on solder area.
  - 2.2: Fit: Tin plated over Nickel.



RECOMMENDED FPC/FFC DIMENSION

PIN	DIM A	DIM B	DIM C	PIN	DIM A	DIM B	DIM C
04	3.00	5.10	9.05	18	17.00	19.10	23.05
05	4.00	6.10	10.05	19	18.00	20.10	24.05
06	5.00	7.10	11.05	20	19.00	21.10	25.05
07	6.00	8.10	12.05	21	20.00	22.10	26.05
08	7.00	9.10	13.05	22	21.00	23.10	27.05
09	8.00	10.10	14.05	23	22.00	24.10	28.05
10	9.00	11.10	15.05	24	23.00	25.10	29.05
11	10.00	12.10	16.05	25	24.00	26.10	30.05
12	11.00	13.10	17.05	26	25.00	27.10	31.05
13	12.00	14.10	18.05	27	26.00	28.10	32.05
14	13.00	15.10	19.05	28	27.00	29.10	33.05
15	14.00	16.10	20.05	29	28.00	30.10	34.05
16	15.00	17.10	21.05	30	29.00	31.10	35.05
17	16.00	18.10	22.05				

DIM	TOL
x	±0.25
x.x	±0.20
x.xx	±0.10
x.xxx	±0.05

<b>SUNFUN</b>		<b>SUNFUN TECHNOLOGY LTD</b>			
DRAW NO.	FDS1020(A0)	DATE	02/28'12	MATERIAL:	SEE NOTES
DESIGN:	Orlando	02/28'12	FINISH:	SEE NOTES	DRAW NAME: FPC CONN- Drawer type Pitch 1.0 / Height 2.0mm Sub contact / SMT Type.
CHECK:	Orlando	02/28'12	FILE:	FDS1020(A0)	MODEL: P1.0 FPC CONN
REVIEW:	Yale	02/28'12	P/N:	FDS1020(A0)-XX(11R)	UNIT: mm SHEET: 1/1
APPROVED	Yale	02/28'12	REV. A0	SCALE	